AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

LISTING OF CLAIMS:

- 1. (Currently amended) A photosensitive resin composition comprising:
- (A) a binder polymer,
- (B) a photopolymerizing compound with at least one polymerizable ethylenic unsaturated group in the molecule and
- (C) a photopolymerization initiator, wherein component (B) contains a compound represented by the following general formula (1):-

[Chemical Formula 5]

(wherein the three R¹ groups each independently represent hydrogen or methyl, the three X groups each independently represent C2-6 alkylene and i, j and k each independently represent an integer of 1-14-).

2. (Original) A photosensitive resin composition according to claim 1, wherein the alkylene group of component (B) is ethylene or propylene.

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3. (Currently amended) A photosensitive resin composition according to claim 1-or-2, wherein the compound represented by general formula (1) above is a compound represented by the following general formula (2):-

[Chemical Formula 6]

(wherein the three R^1 groups each independently represent hydrogen or methyl, the three X^1 and three X^2 groups each independently represent C2-6 alkylene and I, m, n, p, q and r each independently represent an integer of 1-7-).

- 4. (Original) A photosensitive resin composition according to claim 3, wherein X^1 and X^2 on the same chain in component (B) are different alkylene groups.
- 5. (Currently amended) A photosensitive resin composition according to claim 3-or-4, wherein either of X^1 and X^2 in component (B) is an ethylene group and the other is a propylene group.
- 6. (Currently amended) A photosensitive resin composition according to <u>claim 3any one of claims 3 to 5</u>, wherein I, m, n, p, q and r in component (B) each independently represent an integer of 1-3.

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7. (Currently amended) A photosensitive resin composition according to

claim 1any one of claims 1 to 6, wherein the weight-average molecular weight of

component (A) is 10,000-95,000.

8. (Currently amended) A photosensitive resin composition according to

claim 1any one of claims 1 to 7, which has a component (A) content of 40-80 parts

by weight, a component (B) content of 20-60 parts by weight and a component (C)

content of 0.1-20 parts by weight with respect to 100 parts by weight as the total of

component (A) and component (B).

9. (Currently amended) A photosensitive resin composition according to

claim 1 any one of claims 1 to 8, wherein the content of the compound represented

by general formula (1) above is 5-60 wt% with respect to the total of component (B).

10. (Currently amended) A photosensitive element provided with a support

and a photosensitive layer comprising a photosensitive resin composition according

to claim 1 any one of claims 1 to 9 formed on said support.

11. (Original) A photosensitive element according to claim 10, wherein the

thickness of said support is 5-25 µm.

12. (Currently amended) A photosensitive element according to claim 10

or 11, wherein the haze of said support is 0.001-5.0.

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13. (Currently amended) A photosensitive element according to <u>claim</u>

10 any one of claims 10 to 12, wherein said photosensitive layer has an ultraviolet

light transmittance of 5-75% at a wavelength of 365 nm.

14. (Currently amended) A photosensitive element according to claim

10 any one of claims 10 to 13, which is further provided with a protective film on said

photosensitive layer.

15. (Original) A photosensitive element according to claim 14, wherein the

thickness of said protective film is 5-30 µm.

16. (Currently amended) A photosensitive element according to claim 14

or 15, wherein the tensile strength of said protective film in the lengthwise direction

of the film is at least 13 MPa.

17. (Currently amended) A photosensitive element according to claim

14any one of claims 14 to 16, wherein the tensile strength of said protective film in

the widthwise direction of the film is at least 9 MPa.

18. (Currently amended) A resist pattern forming method wherein a

photosensitive layer for a photosensitive element according to claim 10 any one of

claims 10 to 13 is laminated on a circuit-forming board and active light rays are

irradiated onto prescribed sections of said photosensitive layer for photocuring of the

exposed sections, after which the non-exposed sections of said photosensitive layer

are removed.

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19. (Currently amended) A resist pattern forming method wherein the protective film of a photosensitive element according to <u>claim 14</u> any one of claims 14 to 17 is released at the time the photosensitive layer of said photosensitive element is laminated on a circuit-forming board, and active light rays are irradiated onto prescribed sections of said photosensitive layer for photocuring of the exposed sections, after which the non-exposed sections of said photosensitive layer are removed.

20. (Currently amended) A printed circuit board production process wherein a circuit-forming board having a resist pattern formed thereon by a resist pattern forming method according to claim 18-or-19 is etched or plated.